

DB3S308F

Silicon epitaxial planar type

For high speed switching circuits

■ Features

- Short reverse recovery time t_{rr}
- Low forward voltage V_F
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Basic Part Number

Dual DB2S308 (Series)

■ Packaging

Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Repetitive peak reverse voltage	V_{RRM}	30	V
Forward current (Average)	Single	100	mA
	Series	75	
Peak forward current	Single	200	mA
	Series	150	
Non-repetitive peak forward surge current *	I_{FSM}	1	
Junction temperature	T_j	125	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +125	$^\circ\text{C}$

Note) *: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

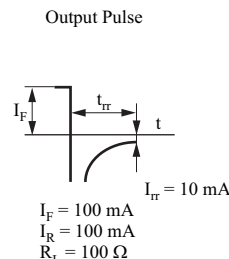
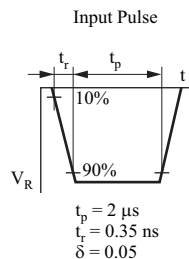
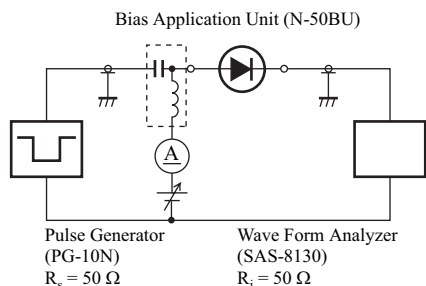
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	$I_F = 10 \text{ mA}$			0.29	V
	V_{F2}	$I_F = 100 \text{ mA}$			0.42	
Reverse current	I_{R1}	$V_R = 10 \text{ V}$			25	μA
	I_{R2}	$V_R = 30 \text{ V}$			120	
Terminal capacitance	C_t	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		2.9		pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 100 \text{ mA}, I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$		1.3		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. Absolute frequency of input and output is 250 MHz

*: t_{rr} measurement circuit



■ Package

• Code

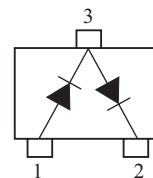
SSMini3-F3-B

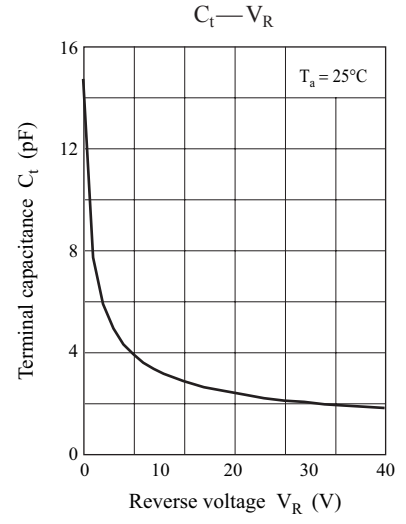
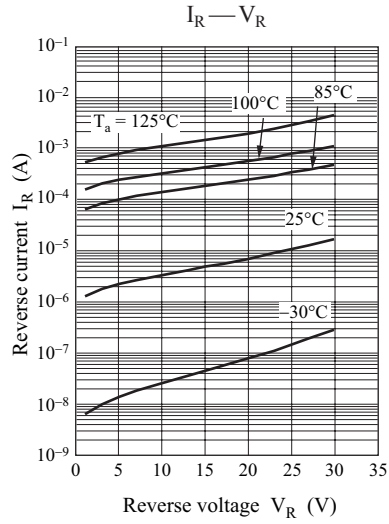
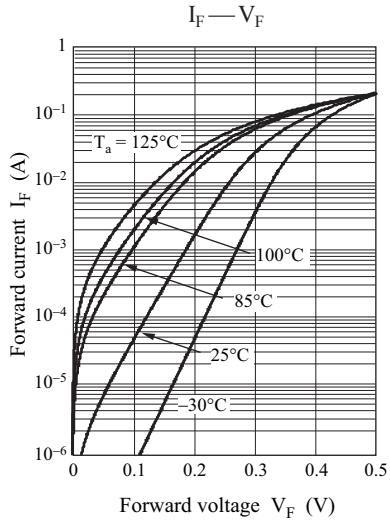
• Pin Name

1: Anode-1 3: Cathode-1
2: Cathode-2 Anode-2

■ Marking Symbol: 4T

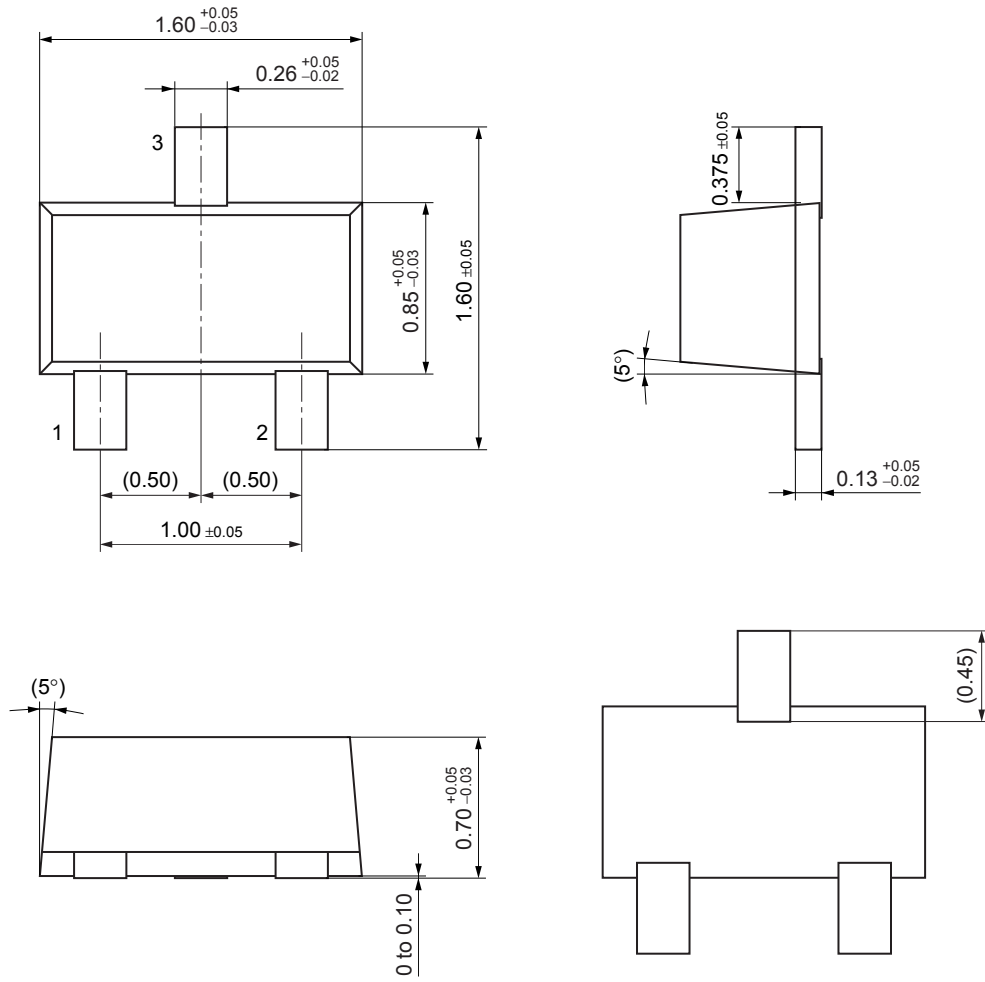
■ Internal Connection





SSMini3-F3-B

Unit: mm



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